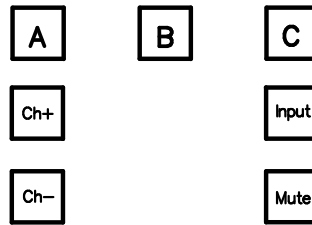
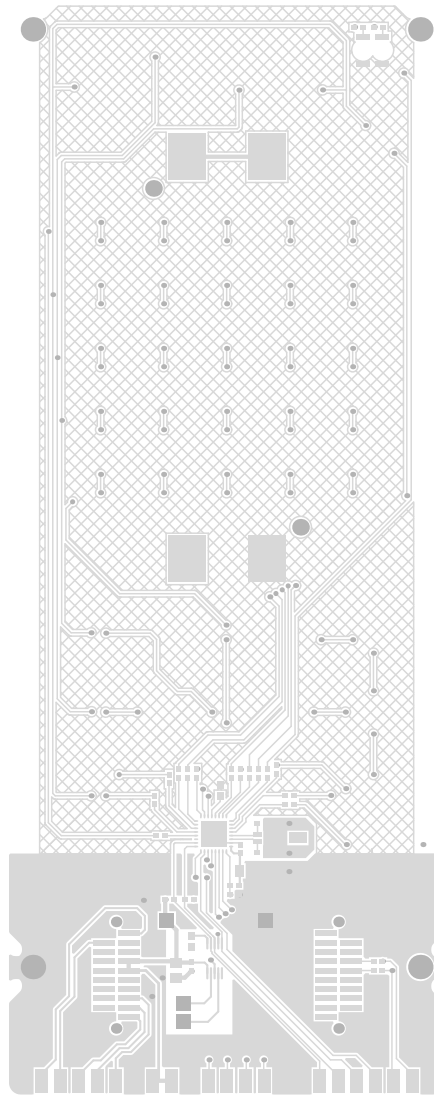


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDM-CAPTIVATE-REMOTECONTROL SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:	TIDM-CAPTIVATE-REMOTECONTROL
PLOT NAME = Top Layer	GENERATED	: 9/14/2016 12:23:35 PM TEXAS INSTRUMENTS

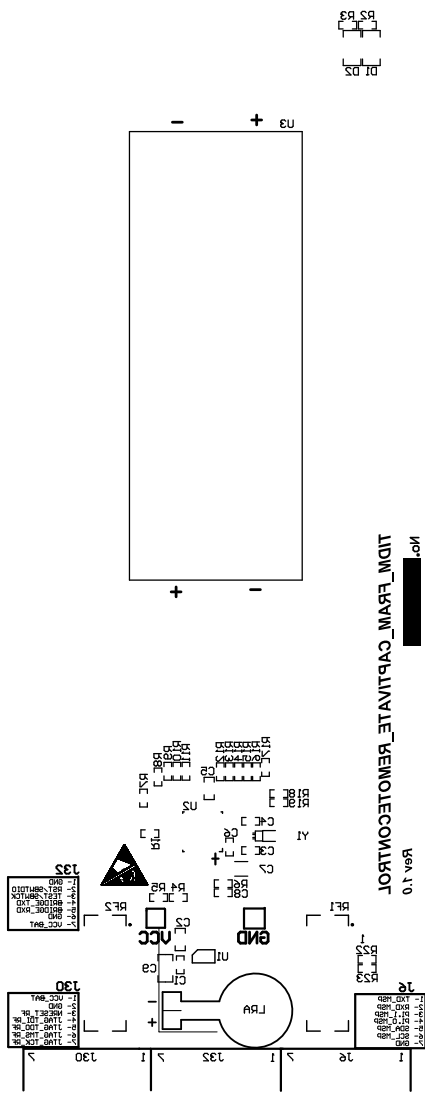


 **TEXAS INSTRUMENTS**
MSP430 CapTivate™ MCUs

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-CAPTIVATE-REMOTECONTROL	DATE: 9/14/2016	TIME: 12:23:36 PM	REV: Not In Version Control
LAYER NAME = Top Overlay	TID #: TIDM-CAPTIVATE-REMOTECONTROL			
PLOT NAME = Top Overlay	GENERATED	: 9/14/2016	12:23:36 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-CAPTIVATE-REMOTECONTROL SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDM-CAPTIVATE-REMOTECONTROL
PLOT NAME = Bottom Layer	GENERATED : 9/14/2016 12:23:37 PM TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-CAPTIVATE-REMOTECONTROL SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDM-CAPTIVATE-REMOTECONTROL
PLOT NAME = Bottom Overlay	GENERATED : 9/14/2016 12:23:38 PM
	TEXAS INSTRUMENTS

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